MURHB860CT

Preferred Device

MEGAHERTZ™ Power Rectifier

D²PAK Power Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Package Designed for Power Surface Mount Applications
- Ultrafast 35 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 V
- Low Leakage Specified @ 150°C Case Temperature
- Short Heat Sink Tab Manufactured Not Sheared!
- Similar in Size to Industry Standard TO-220 Package
- Pb–Free Packages are Available

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	600	V
Average Rectified Forward Current (Rated V_R , T_C = 120°C) Total Device	I _{F(AV)}	4.0 8.0	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 120^{\circ}C$)	I _{FM}	8.0	A
Non–Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	100	A
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +175	°C

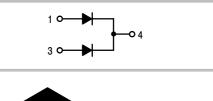
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIER 8.0 AMPERES, 600 VOLTS





MARKING DIAGRAM



A= Assembly LocationY= YearWW= Work WeekUH860= Device CodeG= Pb-Free PackageAKA= Diode Polarity

ORDERING INFORMATION

Device	Package	Shipping [†]
MURHB860CT	D ² PAK	50 Units/Rail
MURHB860CTG	D ² PAK (Pb–Free)	50 Units/Rail
MURHB860CTT4	D ² PAK	800/Tape & Reel
MURHB860CTT4G	D ² PAK (Pb–Free)	800/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

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THERMAL CHARACTERISTICS (Per Leg)

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	$R_{ ext{ heta}JC}$	3.0	°C/W
Maximum Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	50	°C/W

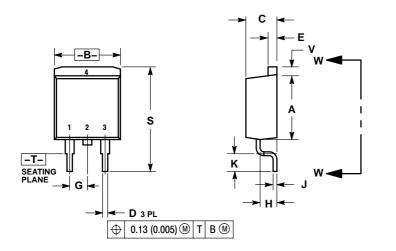
ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 1) ($i_F = 4.0 \text{ A}, T_C = 150^{\circ}\text{C}$) ($i_F = 4.0 \text{ A}, T_C = 25^{\circ}\text{C}$)	VF	2.5 2.8	V
Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, $T_C = 150^{\circ}C$) (Rated DC Voltage, $T_C = 25^{\circ}C$)	i _R	500 10	μΑ
Maximum Reverse Recovery Time (I _F = 1.0 A, di/dt = 50 A/µs)	t _{rr}	35	ns

1. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%

PACKAGE DIMENSIONS

D²PAK 3 CASE 418B–04 ISSUE J



NEW STANDARD 418B-04. INCHES MILLIMETERS DIM MIN MAX MIN MAX A 0.340 0.380 B 0.380 0.405 8.64 9.65 9.65 10.29 4.06 4.83 **C** 0.160 0.190 **D** 0.020 0.035 0.51 0.89 E0.0450.055F0.3100.350 1.14 1.40 7.87 8.89 G 0.100 BSC 2.54 BSC
 H
 0.080
 0.110

 J
 0.018
 0.025
 2.03 2.79 0.46 0.64 K 0.090 0.110 2.29 2.79
 L
 0.052
 0.072

 M
 0.280
 0.320

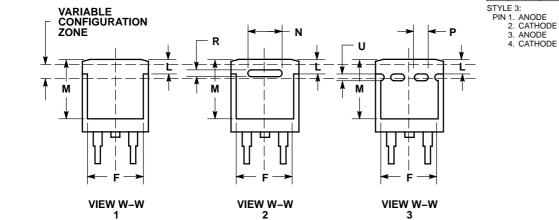
 N
 0.197 REF
 1.32 1.83 7.11 8.13 5.00 REF Ρ 0.079 REF 2.00 REF
 R
 0.039 REF
 0.99 REF

 S
 0.575
 0.625
 14.60
 15.88

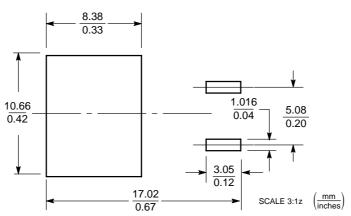
 V
 0.045
 0.055
 1.14
 1.40

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 418B-01 THRU 418B-03 OBSOLETE,

NOTES:



SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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